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Title of Invention: THIN AND HEAT RADIANT
SEMICONDUCTOR PACKAGE AND
METHOD FOR MANUFACTURING

First Named Inventor: Jae Ku

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TRANSMITTAL

Electronic Version v1.1

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Title of Invention	THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING	
Application Number: 10/665651 *10/665651*		
Date: 2003-09-19		
First Named Applicant: Jae Hun Ku		
Confirmation Number: 6079		
Attorney Docket Number: AMKOR041G		
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Submitted by:	Elec. Sign.	Sign. Capacity
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Comments	

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING						
 Application Number: 10/665651 *10/665651* Confirmation Number: 6079 First Named Applicant: Jae Ku Attorney Docket Number: AMKOR041G Art Unit: 2811 Search string: (6197615 or 6198171 or 6201186 or 6201292 or 6204554 or 6208020 or 6208021 or 6208023 or 6211462 or 6218731 or 6222258 or 6225146 or 6229200 or 6229205 or 6239367 or 6239384 or 6242281 or 6256200 or 6258629 or 6281566 or 6281568 or 6282095 or 6285075 or 6291271 or 6291273 or 6294100 or 6294830 or 6295977 or 6297548 or 6303984 or 6303997 or 6307272 or 6309909 or 6316822 or 6316838 or 6323550 or 6326243 or 6326244 or 6326678 or 6335564 or 6337510 or 6339255 or 6348726 or 6355502 or 6369447 or 6369454 or 6373127 or 6380048 or 6384472 or 6388336).pn. US Patent Documents Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Signature

Examiner Name	Date